

## **ABSTRACT OF THE DISCLOSURE**

A high-frequency circuit comprises a substrate having an electronic component on an obverse side thereof, a first ground pattern formed on almost an entire reverse side of the substrate, a microstrip line formed on the obverse side of the substrate, and a bias line connected to the electronic component on the obverse side of the substrate and formed continuously on the obverse side and the reverse side of the substrate so as to cross the microstrip line on the reverse side of the substrate in plan view so as to supply a bias voltage to the electronic component, wherein the first ground pattern is formed so as to circumvent the bias line formed on the reverse side of the substrate, a portion of the first ground pattern that circumvents the bias line on the reverse side of the substrate is continuously formed on the obverse side of the substrate as a second ground pattern so as to divide the microstrip line in two parts, and a chip jumper is arranged to bridge the two divided parts of the microstrip line over the second ground pattern so as to connect the divided microstrip line electrically.